

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-7. (canceled).

8. (currently amended): A sealing material comprising a fluorine-containing elastomer composition comprising a perfluoroelastomer and an inorganic filler, said inorganic filler consisting of a crystalline carbon allotrope having an average primary particle size of at most 0.1 μm .

9. (previously presented): The sealing material of Claim 8, wherein the crystalline carbon allotrope having an average primary particle size of at most 0.1 μm is diamond.

10. (canceled).

11. (previously presented): The sealing material for a semiconductor manufacturing equipment of Claim 8.

12-15. (canceled).

16. (new): The sealing material of Claim 8, wherein the sealing material does not contain an inorganic filler other than the crystalline carbon allotrope having an average primary particle size of at most 0.1 μm .

17. (new): A sealing material comprising a perfluoroelastomer composition comprising a perfluoroelastomer and a crystalline carbon allotrope having an average primary particle size of at most 0.1 μm , said sealing material not containing a metal compound inorganic filler.